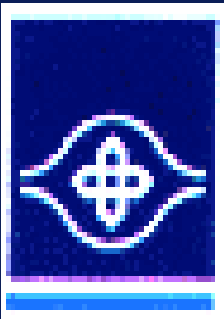

2021 Q1 Operation Briefing of Nan Ya PCB Corp.

July 6th 2021



Disclaimer

The description of historical events might include the information that was not reviewed by accountants. Thus, it might be insufficient to fully exhibit the financial status or operation results of Nan Ya PCB Corp.

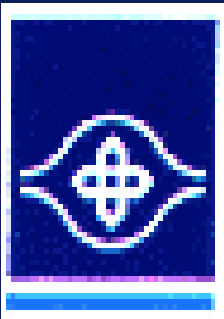
The actual operation results, financial status, and sales outlook in the future might be different from what will be indicated or implied in this meeting. The reasons may be including but not limited to the market demand, price fluctuation, competition dynamic, global economy, supply-chain, foreign exchange rate, and other risks that the Company cannot control.

Except as required by law, we undertake no obligation to update any forward-looking statement, whether as a result of new information, future events, or otherwise.



Agenda

- **Company Profile**
- **Financial Status**
- **Future Product Development**
- **Operational Goals**



Company Profile

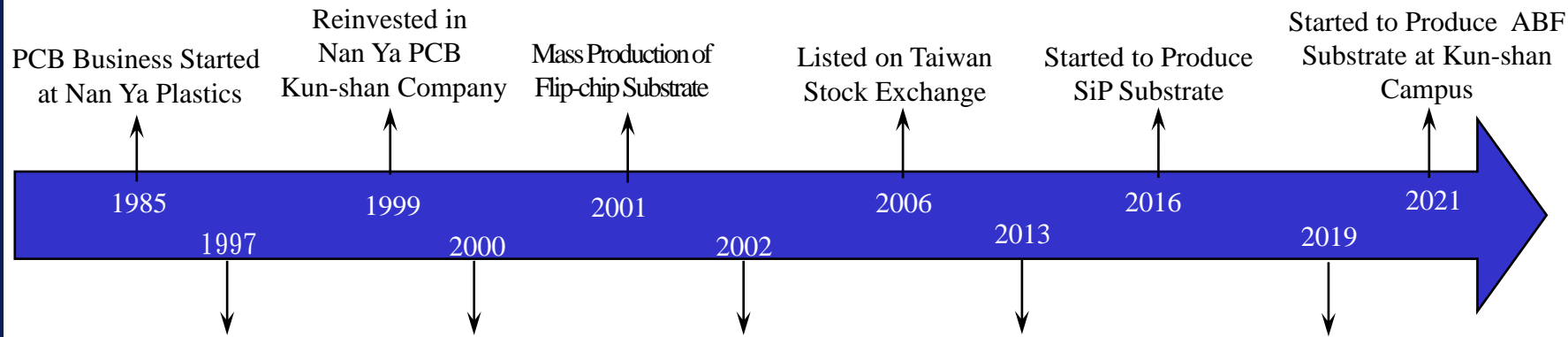
Business Overview

- **Subsidiary Company of Nan Ya Plastics Corp.**
- **Manufacture and Sell PCBs and IC Substrates**
- **2021 Q1 Consolidated Revenues: NTD 10.8 Billion**
- **Market Value: NTD 228.7 Billion(March 31st 2021)**
- **Production Locations : Taiwan and China**



Company Profile

Milestone



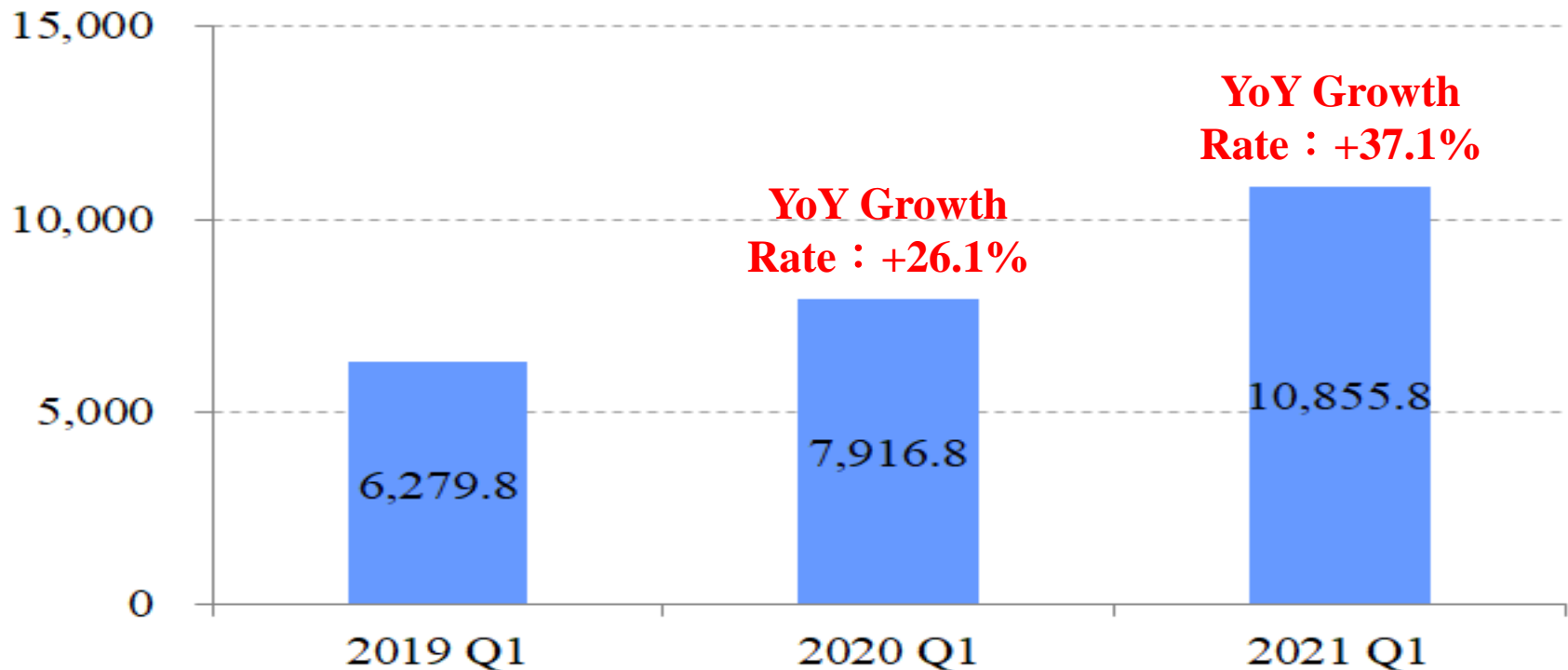
- **1985 : PCB business unit was formed at Nan Ya Plastics Corp. and started manufacturing PCBs**
- **1997 : Approved by the Board of Nan Ya Plastics, Nan Ya PCB Corp. was established via reinvestment**
- **1999 : Reinvested Nan Ya PCB Kun-shan Company with capital of USD29.8 million**
- **2000 : Started manufacturing wire-bonding substrates**
- **2001 : Upgraded technologies and produced flip-chip substrates**
- **2002 : Established Nan Ya PCB America Corp.**
- **2006 : Listed on Taiwan Stock Exchange with ticker 8046 TT**
- **2013 : Upgraded technologies and produced Embedded substrates**
- **2016 : Started to produce System in Package (SiP) substrates**
- **2019 : In response to market demand, Nan Ya PCB Corp. started to build ABF substrate production line at Kun-shan Campus**
- **2021 : Kun-shan Campus started to manufacture ABF substrates**



Financial Status

Q1 Consolidated Revenues(IFRS) in Last 3 Years

(NTD Million)

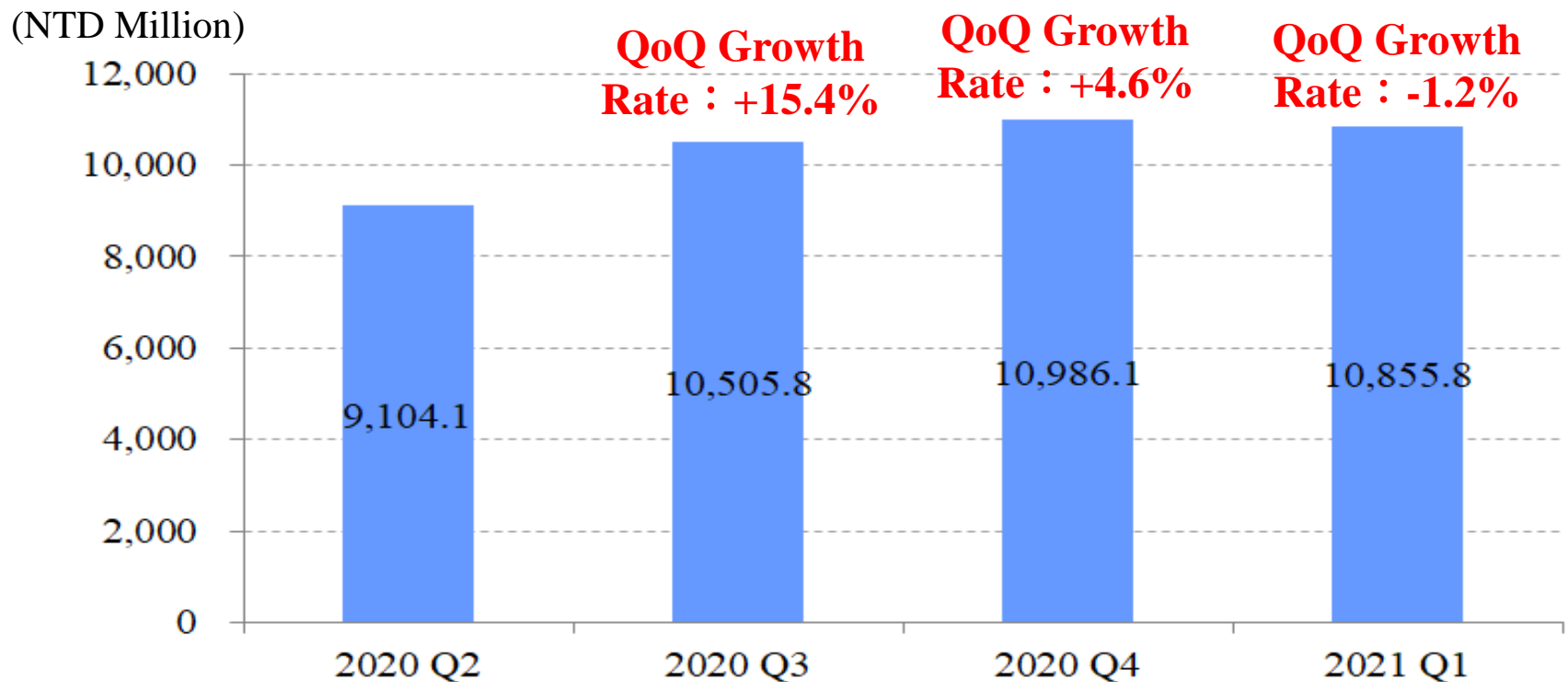


- **Revenues in 2020 Q1 were 26.1% greater than those in 2019 Q1:**
Nan Ya PCB was an early entrant in high-end telecom and SiP substrate fields and benefited from the increase in customer demands, and the 2020 revenues grew significantly from 2019.
- **Revenues in 2021 Q1 were 37.1% greater than those in 2020 Q1**
Nan Ya PCB was helped by WFH and stay home entertainments, and the 2021 Q1 performance was better than that in 2020 Q1.



Financial Status

Quarterly Consolidated Revenues(IFRS) in a Year

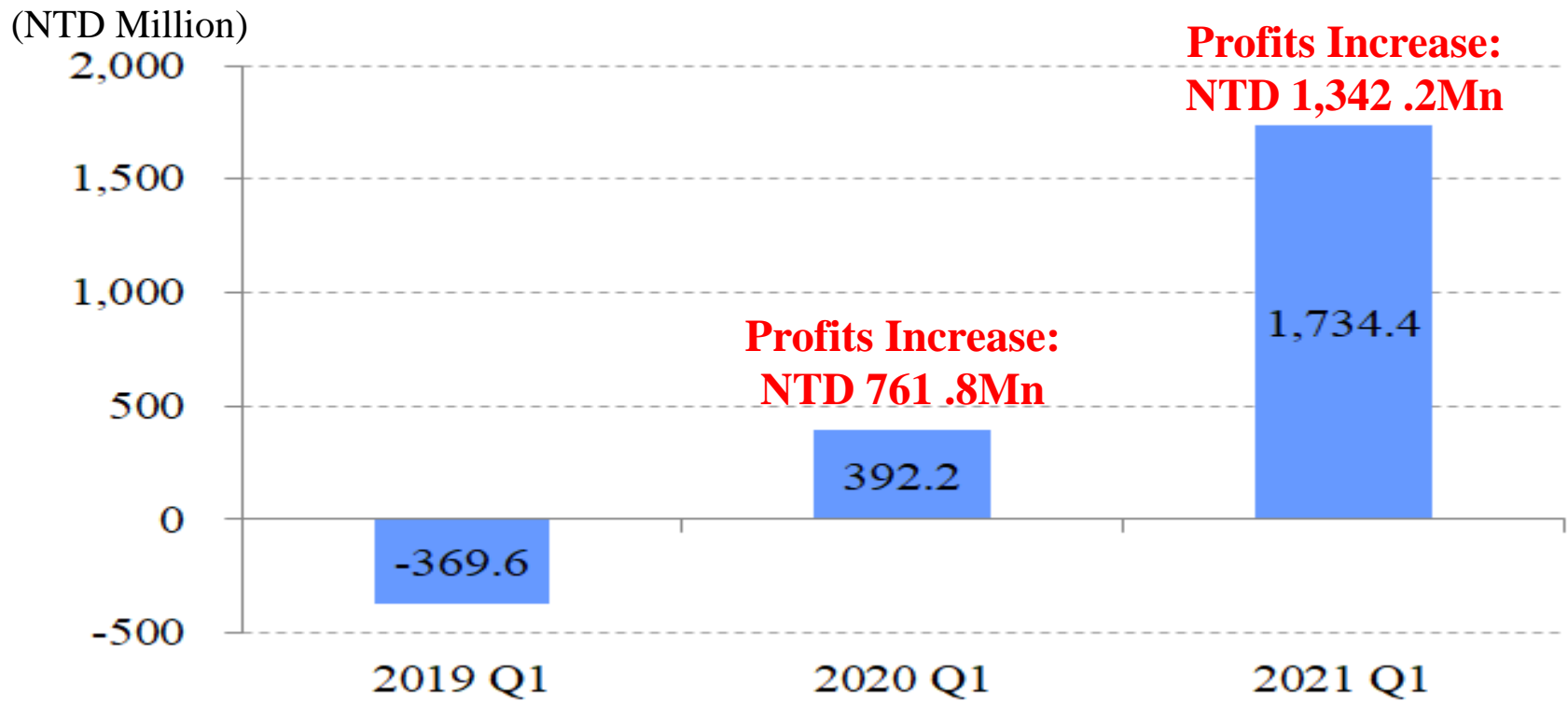


- **Revenues in 20Q3 were 15.4% greater than those in 20Q2:**
Helped by rising demands in telecom and consumer electronics, 20Q3 sales kept growing.
- **Revenues in 20Q4 were 4.6% greater than those in 20Q3:**
Increasing demands in the PC, telecom, and automotive electronics boosted the Q4 revenues and achieved our goal, consecutive growth of quarterly revenues.
- **Revenues in 21Q1 were 1.2% lower than those in 20Q4:**
Because of fewer working days, revenues in 21Q1 slightly decreased from 20Q4.



Financial Status

Q1 Operation Profits(Losses) in Last 3 Years



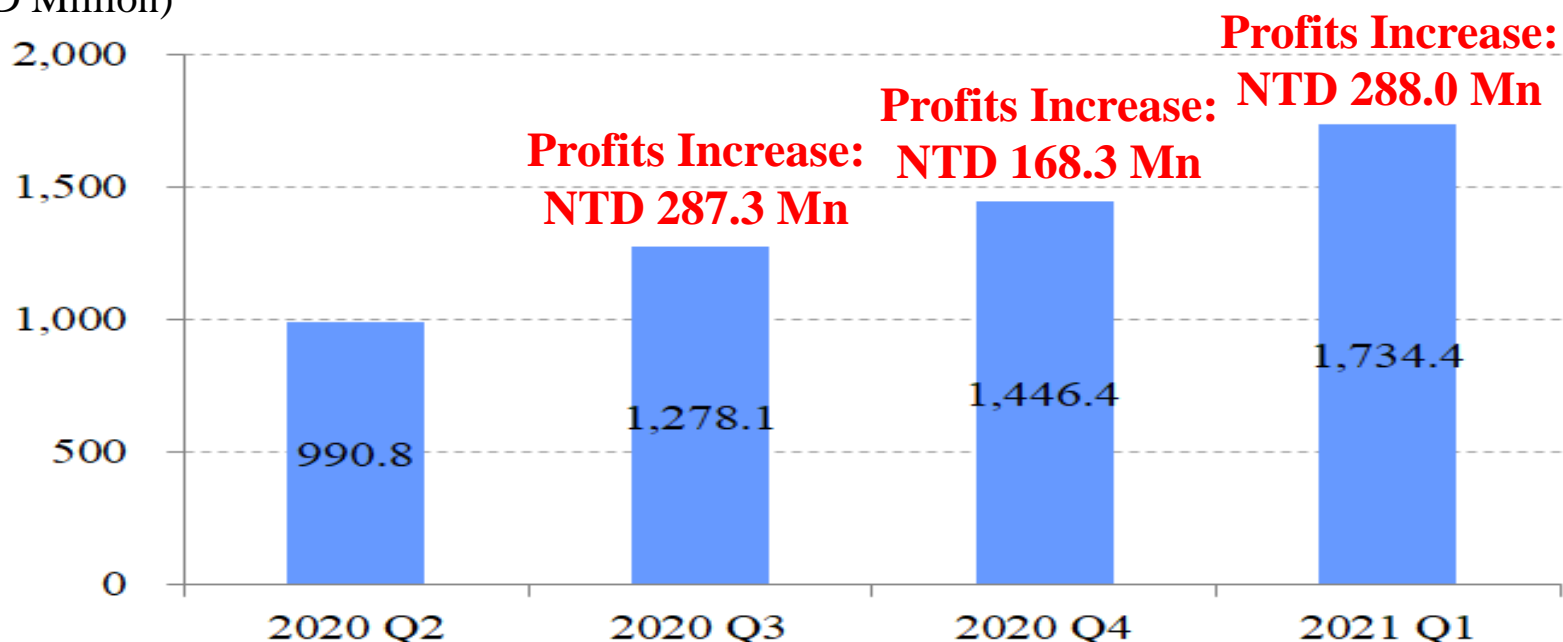
- **Operation profits in 2020 Q1 were increasing NTD 761.8 Mn from 2019 Q1:**
The 2020 Q1 operation profits grew significantly because of improved yield rate and better product mix due to more high-end telecom products.
- **Operation profits in 2021 Q1 were increasing NTD 1,342.2 Mn from 2020 Q1:**
The product mix continued to be enhanced by the help from better high value product sales, such as high-end CPU and GPU substrates. Thus, 2021 Q1 operation profits kept growing.



Financial Status

Quarterly Operation Profits in a Year

(NTD Million)



- **Operation profits in 20Q3 were increasing NTD 287.3 Mn from 20Q2:**

The 20Q3 operation profits were greater than 20Q2 because of increasing sales in high value products such as high-end telecom substrates, SiP substrates and interposers.

- **Operation profits in 20Q4 were increasing NTD 168.3 Mn from 20Q3:**

Ring sales of telecom, NBs, game consoles, automotive electronics, and etc. lifted 20Q4 operation profits, matching our target of consecutive quarterly operation profits growth.

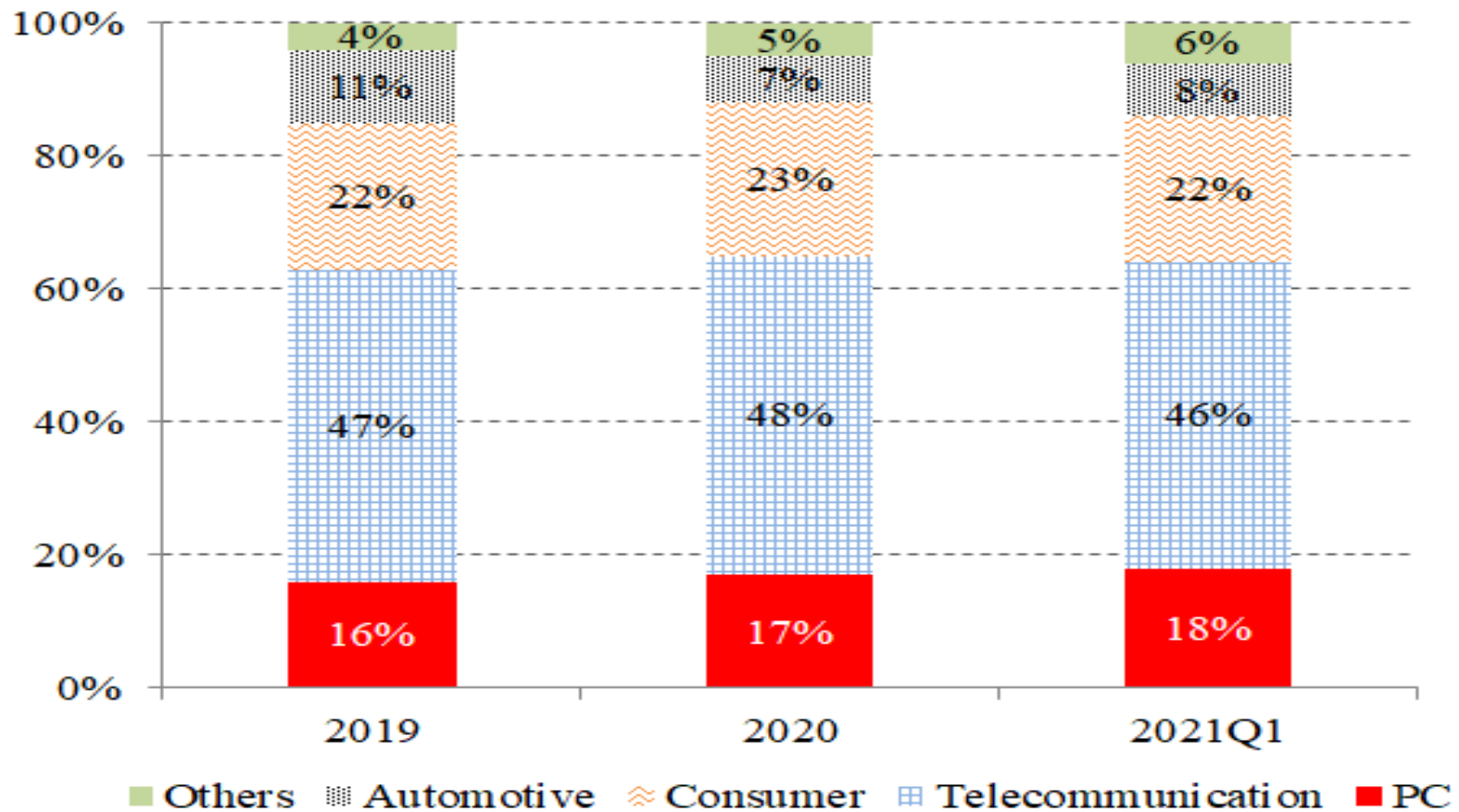
- **Operation profits in 21Q1 were increasing NTD 288.0 Mn from 20Q4:**

Because of better sales in high value products, such as high-end CPU and GPU substrates, 2021 Q1 operation profits continued to grow.



Financial Status

Revenue Structure(By Applications)

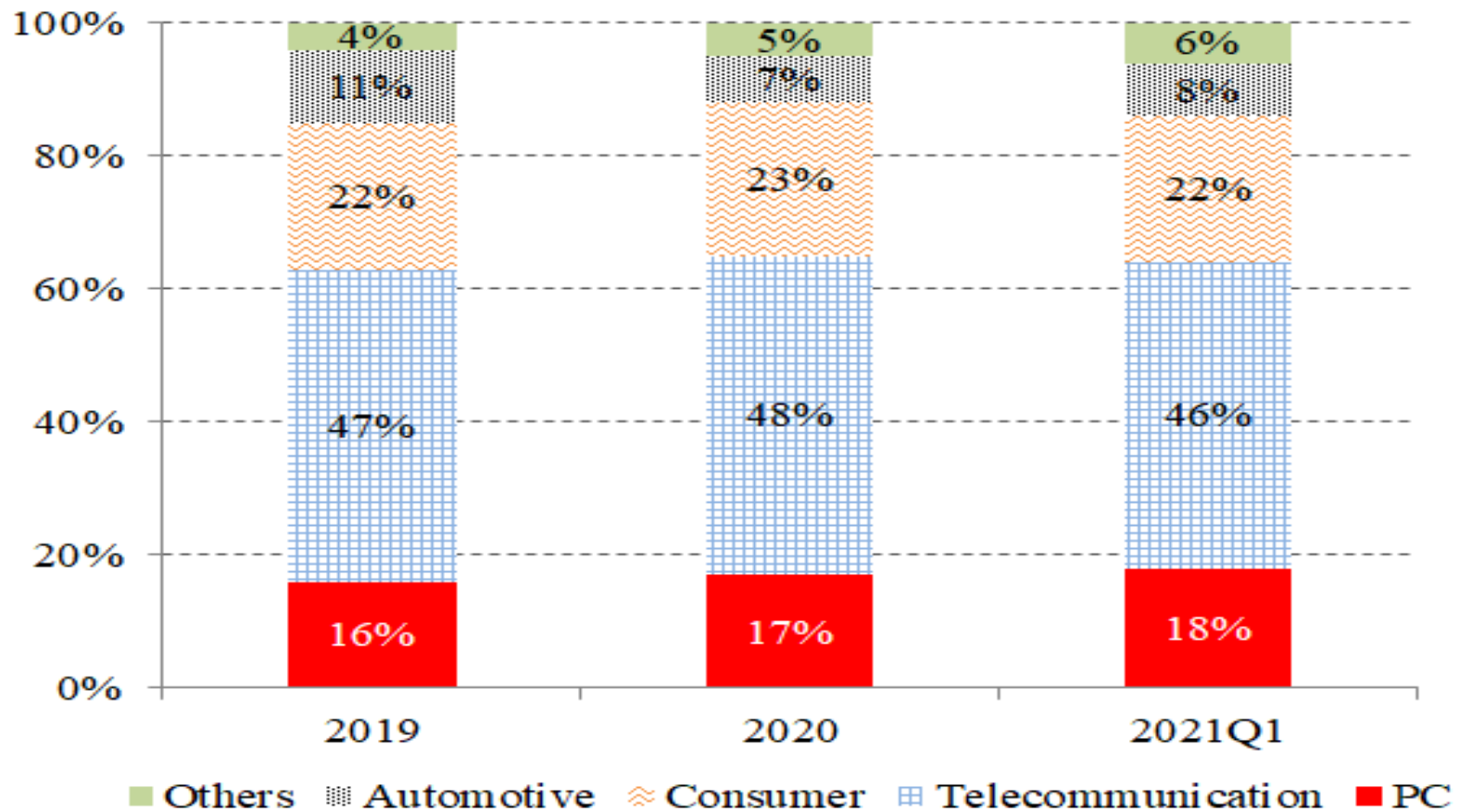


- Because of better demands in PCs products driven by work from home, related revenue ratios in 2021 Q1 grew from 2020.
- Due to the slow season for the mobile phone and true wireless stereo, related revenue ratios in 2021 Q1 declined from 2020.



Financial Status

Revenue Structure(By Applications)



- The automobile market was benefited from the easing COVID-19 situation in Europe and America, leading to our rising automotive product revenue ratio in 2021 Q1.
- Nan Ya PCB actively explored the AI and HPC fields and successfully gained more high value orders from those areas. Thus, the revenue ratio of others continued to grow in 2021Q1.



Future Product Development

Continue to Expand High Value Products

■ High-end ABF Substrate

In 2021, not only will we continue to plow high-end telecom markets, but also expand our market share in AI and HPC products. Additionally, the demands in work from home and stay at home economics are expected to grow, and we will keep producing substrates for high-end processors and graphic chips to further enlarge our market share.

■ SiP(System in Package) Substrate

Given the trend of heterogeneous integration remains, SiP technologies will be applied to all sorts of mobile device. We will continue to produce SiP substrates for new generation wearable device and camera modules in high-end smartphones. Also we will evaluate our capacities to penetrate the antenna in package modules. Our SiP substrate sales are expected to grow.

■ HDI

As the designs of handset, consumer electronics, and automotive electronics are becoming sophisticated, the consumption of high value HDI is increasing. Thus, we will roll out HDI for new generation memories, solid state drive, and infotainment systems to meet the growing demands in notebook PCs and automobiles to boost our profits.



Operational Goals

The Company Seeks Continuous Operation Profits Growth

■ Profits in 21H2 is expected to grow

IC substrates are severely undersupply. Our new IC substrate capacities in Kunshan campus have been full run in 21Q2 and we have rented a plant in Taiwan from Nan Ya Plastic Corp. for further expanding the capacities of high-end IC substrates, which will start production in the end of 2021, in order to spur revenues and profits. Additionally, we apply AI to our manufacturing management to improve yield rate and efficiencies. With the synergy of the hardware and software, our 21H2 profits are expected to grow from 21H1.

■ To Seek quarter on quarter profit growth in 2021

Sales Expansion: Nan Ya PCB will continue the operation strategies in 2020 to develop CPU, high-end telecom equipment, AI, HPC, and high-end automotive application substrates and PCBs. Also, we will continue to de-bottleneck to increase output and meet clients' needs.

Costs Reduction: We will continue to improve the yield rate and efficiency through strengthening manufacturing processes. Also, we will implement digital management to further enhance performance. This year, we will strive to achieve the goal of consecutive quarterly growth of our profits.



Thank You

